

0.5A Avg.

40 Volts

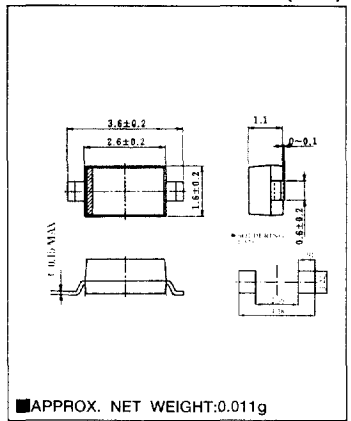
SBD

EP05Q04

■最大定格 MAXIMUM RATINGS

Rating	Type	EP05Q04	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	$V_{RRM}$	40	V
平均整流電流 Average Rectified Output Current	Glass-Epoxy Substrate mounted *	0.43 (商用周波数、正弦波180度通電 $T_a=25^{\circ}C$ ) Half Sine Wave, Resistive Load	A
		0.50 (商用周波数、正弦波180度通電 $T_l=110^{\circ}C$ ) Half Sine Wave, Resistive Load (TL: Lead Temperature)	A
実効順電流 RMS Forward Current	$I_F(RMS)$	0.785	A
サージ順電流 Surge Forward Current	$I_{FSM}$	8 (50Hz単相正弦半波1サイクル非くり返し) Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	$T_{jw}$	-40~+150	$^{\circ}C$
保存温度範囲 Storage Temperature Range	$T_{stg}$	-40~+150	$^{\circ}C$

■OUTLINE DRAWING(mm)



■電気的特性 ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	$I_{RM}$	$V_{RM}=V_{RRM}$ $T_j=25^{\circ}C$	—	—	100	$\mu A$
ピーク順電圧 Peak Forward Voltage	$V_{FM}$	$I_{FM}=0.5A$ $T_j=25^{\circ}C$	—	—	0.51	V
熱抵抗 Thermal Resistance	接合部-周囲間 (Junction to Ambient)	Glass-Epoxy Substrate mounted *	—	—	300	$^{\circ}C/W$
	接合部-リード間 (Junction to Lead)		—	—	70	$^{\circ}C/W$

\* Soldering Lands = 1×1 mm, Both Sides

■定格・特性曲線

FIG.1

順電圧特性  
FORWARD CURRENT VS. VOLTAGE

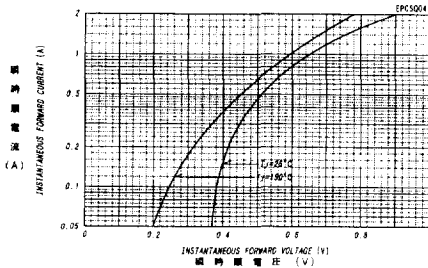


FIG.4

平均逆電力損失  
AVERAGE REVERSE POWER DISSIPATION

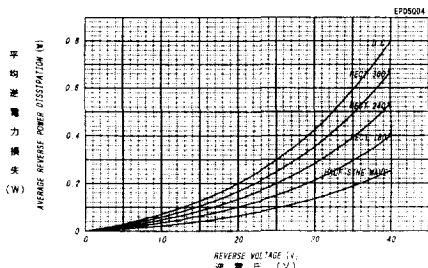


FIG.7

サージ順電流定格  
SURGE CURRENT RATINGS

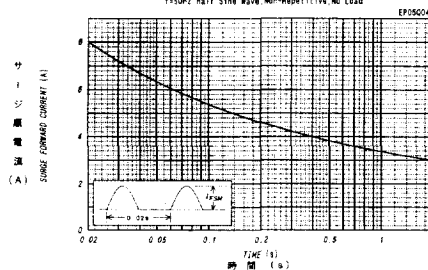


FIG.2

平均順電力損失特性  
AVERAGE FORWARD POWER DISSIPATION

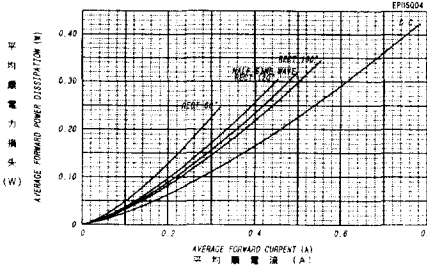


FIG.5

平均順電流-周囲温度定格  
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

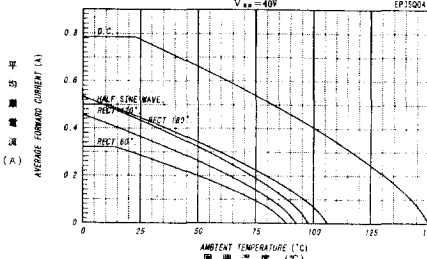


FIG.8

接合容量特性  
JUNCTION CAPACITANCE VS. REVERSE VOLTAGE

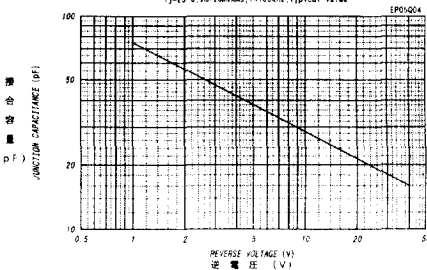


FIG.3

ピーク逆電流 - ピーク逆電圧特性  
PEAK REVERSE CURRENT VS. PEAK REVERSE VOLTAGE

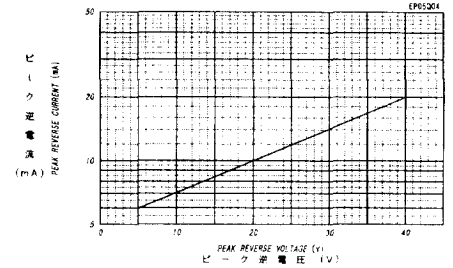


FIG.6

平均順電流-リード温度定格  
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

